## PNP Silicon General Purpose Amplifier Transistor

This PNP transistor is designed for general purpose amplifier applications. This device is housed in the SC-75/SOT-416/SC-90 package which is designed for low power surface mount applications, where board space is at a premium.

#### **Features**

- Reduces Board Space
- High h<sub>FE</sub>, 210-460 (typical)
- Low V<sub>CE(sat)</sub>, < 0.5 V
- Available in 8 mm, 7-inch/3000 Unit Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>(BR)CBO</sub>	-60	Vdc
Collector – Base Voltage	V <sub>(BR)CEO</sub>	-50	Vdc
Emitter - Base Voltage	V <sub>(BR)EBO</sub>	-6.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	-100	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 1)	$P_{D}$	150	mW
Junction Temperature	TJ	150	°C
Storage Temperature Range	T <sub>stq</sub>	−55 ~ + 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.

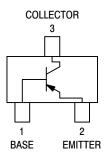


### ON Semiconductor®

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SC-75 CASE 463 STYLE 1



#### **MARKING DIAGRAM**



F9 = Device Code
M = Date Code\*
= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
2SA1774G	SC-75 (Pb-Free)	3,000/Tape & Reel
S2SA1774G	SC-75 (Pb-Free)	3,000/Tape & Reel
2SA1774T1G	SC-75 (Pb-Free)	3,000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ )

Characteristic	Symbol	Min	Тур	Max	Unit
Collector–Base Breakdown Voltage ( $I_C = -50 \mu Adc, I_E = 0$ )	V <sub>(BR)CBO</sub>	-60	-	-	Vdc
Collector–Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	-50	-	-	Vdc
Emitter–Base Breakdown Voltage ( $I_E = -50 \mu Adc, I_E = 0$ )	V <sub>(BR)EBO</sub>	-6.0	-	-	Vdc
Collector–Base Cutoff Current $(V_{CB} = -30 \text{ Vdc}, I_E = 0)$	I <sub>CBO</sub>	-	-	-0.5	nA
Emitter-Base Cutoff Current (V <sub>EB</sub> = -5.0 Vdc, I <sub>B</sub> = 0)	I <sub>EBO</sub>	-	-	-0.5	μΑ
Collector–Emitter Saturation Voltage (Note 2) (I <sub>C</sub> = –50 mAdc, I <sub>B</sub> = –5.0 mAdc)	V <sub>CE(sat)</sub>	-	-	-0.5	Vdc
DC Current Gain (Note 2) (V <sub>CE</sub> = -6.0 Vdc, I <sub>C</sub> = -1.0 mAdc)	h <sub>FE</sub>	120	-	560	-
Transition Frequency ( $V_{CE} = -12$ Vdc, $I_{C} = -2.0$ mAdc, $f = 30$ MHz)	f <sub>T</sub>	-	140	-	MHz
Output Capacitance (V <sub>CB</sub> = -12 Vdc, I <sub>E</sub> = 0 Adc, f = 1 MHz)	C <sub>OB</sub>	_	3.5	_	pF

<sup>2.</sup> Pulse Test: Pulse Width ≤ 300 μs, D.C. ≤ 2%.

#### TYPICAL ELECTRICAL CHARACTERISTICS

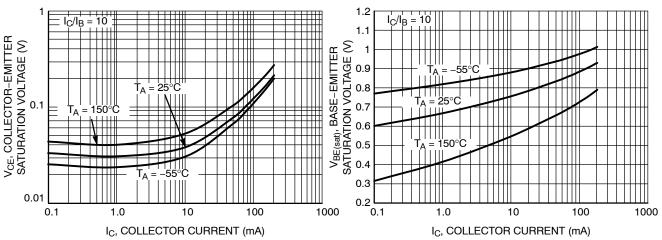


Figure 1. Collector-Emitter Saturation Voltage vs. Collector Current

Figure 2. Base–Emitter Saturation Voltage vs.
Collector Current

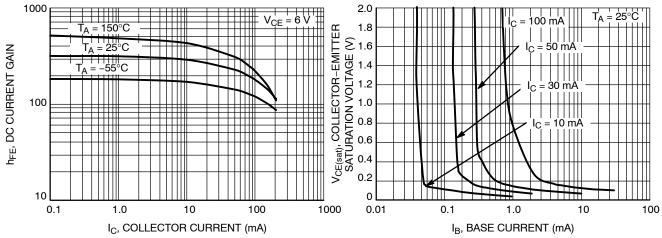


Figure 3. DC Current Gain vs. Collector Current

Figure 4. Saturation Region

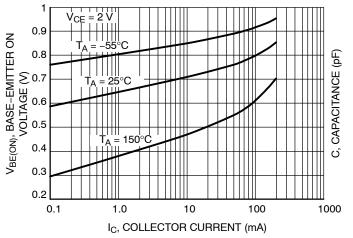


Figure 5. Base-Emitter Turn-ON Voltage vs.
Collector Current

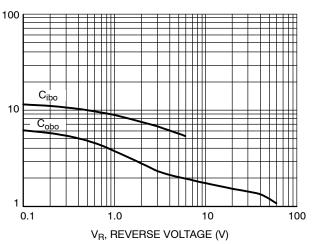


Figure 6. Capacitance

### TYPICAL ELECTRICAL CHARACTERISTICS

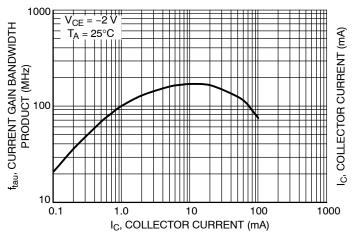


Figure 7. Current Gain Bandwidth Product vs. Collector Current

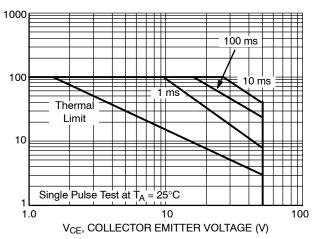
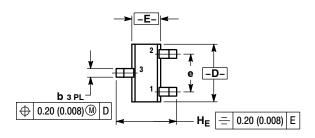
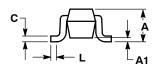


Figure 8. Safe Operating Area

#### PACKAGE DIMENSIONS

SC-75/SOT-416 **CASE 463** ISSUF F





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

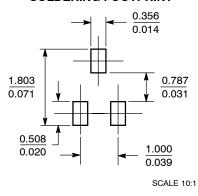
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.80	0.90	0.027	0.031	0.035	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.15	0.20	0.30	0.006	0.008	0.012	
С	0.10	0.15	0.25	0.004	0.006	0.010	
D	1.55	1.60	1.65	0.059	0.063	0.067	
Е	0.70	0.80	0.90	0.027	0.031	0.035	
е	1.00 BSC			0.04 BSC			
L	0.10	0.15	0.20	0.004	0.006	0.008	
HE	1.50	1.60	1.70	0.061	0.063	0.065	

STYLE 1

(mm inches

PIN 1. BASE 2. EMITTER 3. COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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